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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I ² C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc62a-04-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

5.6 I/O Programming Considerations

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

5.6.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bi-directional I/O pin (e.g., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stavs in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read-modify-write instructions (ex. BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-4 shows the effect of two sequential read-modify-write instructions on an I/O port.

EXAMPLE 5-4: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

;Initial PORT settings: PORTB<7:4> Inputs
; PORTB<3:0> Outputs
;PORTB<7:6> have external pull-ups and are
;not connected to other circuitry

;					PORT	latch	PORT	pins
;								
'	BCF	PORTB,	7	;	01pp	pppp	11pp	pppp
	BCF	PORTB,	6	;	10pp	pppp	11pp	pppp
	BSF	STATUS,	RP0	;				
	BCF	TRISB,	7	;	10pp	pppp	11pp	pppp
	BCF	TRISB,	6	;	10pp	pppp	10pp	pppp

;Note that the user may have expected the ;pin values to be 00pp pppp. The 2nd BCF ;caused RB7 to be latched as the pin value ;(high).

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

5.6.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-10). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should be such to allow the pin voltage to stabilize (load dependent) before the next instruction which causes that file to be read into the CPU is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

PC	X PC	X PC + 1	X	PC + 2	(PC + 3)	This example shows a write to POI
Instruction fetched	MOVWF PORTB write to PORTB	MOVF PORTB,W		NOP	NOP	followed by a read from PORTB. Note that:
RB7:RB0	PORTB	1 1 1	X	 	۱ ــــــــــــــــــــــــــــــــــــ	data setup time = (0.25TCY - TPD)
	1 1 1	1 1 1		Port pin sampled here		where TCY = instruction cycle TPD = propagation delay
Instruction executed		MOVWF PORTB write to PORTB	- TPD MO	1	NOP	Therefore, at higher clock frequence a write followed by a read may be p lematic.
	i i	i i		1		

FIGURE 5-10: SUCCESSIVE I/O OPERATION

FIGURE 10-1: CCP1CON REGISTER (ADDRESS 17h) / CCP2CON REGISTER (ADDRESS 1Dh)

U-0	U-0 R/W-0 R	/W-0 R/W-0	R/W-0	R/W-0	R/W-0	
—	- CCPxX CC	CPxY CCPxM3	CCPxM2	CCPxM1	CCPxM0	R = Readable bit
bit7					bit0	W = Writable bit
						U = Unimplemented bit, read as '0'
						- n =Value at POR reset
bit 7-6:	Unimplemented: F	Poad as '0'				
	•					
bit 5-4:	CCPxX:CCPxY: PV	VM Least Significa	ant bits			
	Capture Mode Unused					
	Compare Mode					
	Unused					
	PWM Mode					
	These bits are the t	wo LSbs of the P	NM duty cy	cle. The eig	ht MSbs are	found in CCPRxL.
bit 3-0:	CCPxM3:CCPxM0	: CCPx Mode Sele	ect bits			
	0000 = Capture/Co	•		k module)		
	0100 = Capture mo		•			
	0101 = Capture mo		•			
	0110 = Capture mo	· ·	0 0			
	1000 = Compare m	· ·	• •	CCPxIF is	set)	
	1001 = Compare m		•		,	
	•		•		,	is set, CCPx pin is unaffected)
	•		al event (CC	PxIF bit is s	et; CCP1 res	ets TMR1; CCP2 resets TMR1)
	11xx = PWM mode	9				

10.1 Capture Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Capture mode, CCPR1H:CCPR1L captures the 16-bit value of the TMR1 register when an event occurs on pin RC2/CCP1 (Figure 10-2). An event is defined as:

- · Every falling edge
- · Every rising edge
- · Every 4th rising edge
- Every 16th rising edge

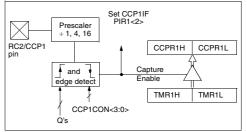
An event is selected by control bits CCP1M3:CCP1M0 (CCP1CON<3:0>). When a capture is made, the interrupt request flag bit CCP1IF (PIR1<2>) is set. It must be cleared in software. If another capture occurs before the value in register CCPR1 is read, the old captured value will be lost.

10.1.1 CCP PIN CONFIGURATION

In Capture mode, the RC2/CCP1 pin should be configured as an input by setting the TRISC<2> bit.

Note:	If the RC2/CCP1 pin is configured as an
	output, a write to PORTC can cause a cap-
	ture condition.

FIGURE 10-2: CAPTURE MODE OPERATION BLOCK DIAGRAM



10.1.2 TIMER1 MODE SELECTION

Timer1 must be running in Timer mode or Synchronized Counter mode for the CCP module to use the capture feature. In Asynchronous Counter mode, the capture operation may not work consistently.

10.1.3 SOFTWARE INTERRUPT

When the Capture event is changed, a false capture interrupt may be generated. The user should clear enable bit CCP1IE (PIE1<2>) to avoid false interrupts and should clear flag bit CCP1IF following any such change in operating mode.

FIGURE 11-13: SPI MODE TIMING (SLAVE MODE WITH CKE = 1) (PIC16C66/67)

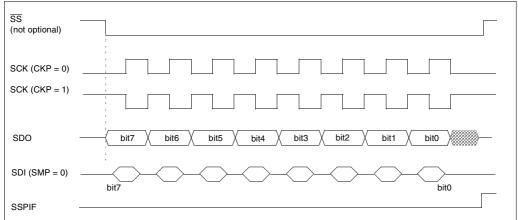


TABLE 11-2:	REGISTERS ASSOCIATED WITH SPI OPERATION	(PIC16C66/67)	

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Pow	e on er-on set		on all resets
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000	000x	0000	000u
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000	0000	0000	0000
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000	0000	0000	0000
13h	SSPBUF	Synchrono	ous Serial	Port Rece	eive Buffe	r/Transmit	Register			xxxx	xxxx	uuuu	uuuu
14h	SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000	0000	0000	0000
85h	TRISA	_	_	PORTA D	ata Direc	tion regist	er			11	1111	11	1111
87h	TRISC	PORTC D	ata Direct	ion registe	n register							1111	1111
94h	SSPSTAT	SMP	CKE	D/A	Р	S	R/W	UA	BF	0000	0000	0000	0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'.

Shaded cells are not used by SSP module in SPI mode.

Note 1: PSPIF and PSPIE are reserved on the PIC16C66, always maintain these bits clear.

2: PIR1<6> and PIE1<6> are reserved, always maintain these bits clear.

12.1.1 SAMPLING

The data on the RC7/RX/DT pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin. If bit BRGH (TXSTA<2>) is clear (i.e., at the low baud rates), the sampling is done on the seventh, eighth and ninth falling edges of a x16 clock (Figure 12-3). If bit BRGH is set (i.e., at the high baud rates), the sampling is done on the 3 clock edges preceding the second rising edge after the first falling edge of a x4 clock (Figure 12-4 and Figure 12-5).

FIGURE 12-3: RX PIN SAMPLING SCHEME (BRGH = 0) PIC16C63/R63/65/65A/R65)

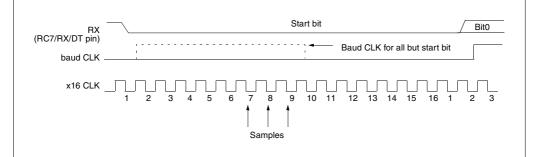
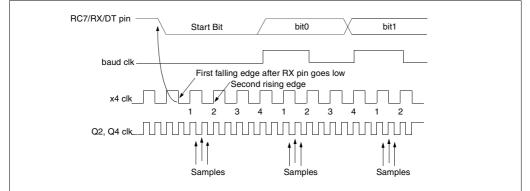
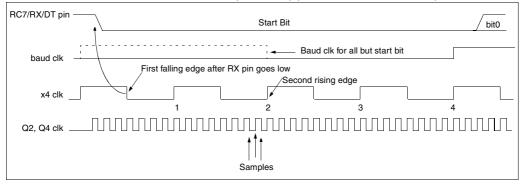


FIGURE 12-4: RX PIN SAMPLING SCHEME (BRGH = 1) (PIC16C63/R63/65/65A/R65)







12.2 USART Asynchronous Mode

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In this mode, the USART uses standard nonreturn-tozero (NRZ) format (one start bit, eight or nine data bits and one stop bit). The most common data format is 8-bits. An on-chip dedicated 8-bit baud rate generator can be used to derive standard baud rate frequencies from the oscillator. The USART transmits and receives the LSb first. The USART's transmitter and receiver are functionally independent but use the same data format and baud rate. The baud rate generator produces a clock either x16 or x64 of the bit shift rate, depending on bit BRGH (TXSTA<2>). Parity is not supported by the hardware, but can be implemented in software (and stored as the ninth data bit). Asynchronous mode is stopped during SLEEP.

Asynchronous mode is selected by clearing bit SYNC (TXSTA<4>).

The USART Asynchronous module consists of the following important elements:

- Baud Rate Generator
- · Sampling Circuit
- Asynchronous Transmitter
- Asynchronous Receiver

12.2.1 USART ASYNCHRONOUS TRANSMITTER

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the STOP bit has been transmitted from the previous load. As soon as the STOP bit is transmitted, the TSR is loaded with new data from the TXREG (if available). Once the TXREG register transfers the data to the TSR register (occurs in one TcY) the TXREG register is empty and flag bit TXIF (PIR1<4>) is set. This interrupt is enabled/dis-

abled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the state of enable bit TXIE and cannot be cleared in software. It will reset only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>) shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty.

Note 1:	The TSR register is not mapped in data
	memory so it is not available to the user.

Note 2: Flag bit TXIF is set when enable bit TXEN is set.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data and the baud rate generator (BRG) has produced a shift clock (Figure 12-7). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register resulting in an empty TXREG register. A back-to-back transfer is thus possible (Figure 12-9). Clearing enable bit TXEN during a transmission will cause the transmistion to be aborted and will reset the transmitter. As a result the RC6/TX/CK pin will revert to hi-impedance.

In order to select 9-bit transmission, transmit bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). In such a case, an incorrect ninth data bit maybe loaded in the TSR register.

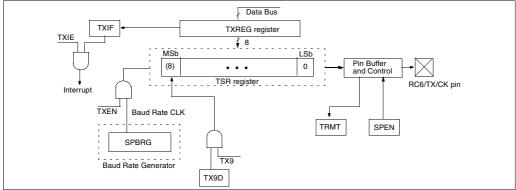


FIGURE 12-7: USART TRANSMIT BLOCK DIAGRAM

TABLE 12-8: REGISTERS ASSOCIATED WITH SYNCHRONOUS MASTER TRANSMISSION

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets	
0Ch	PIR1	PSPIF ⁽¹⁾	(2)	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000	
18h	RCSTA	SPEN	RX9	SREN	CREN		FERR	OERR	RX9D	0000 -00x	x00- 0000	
19h	TXREG	USART Tra	ansmit Re	egister						0000 0000	0000 0000	
8Ch	PIE1	PSPIE ⁽¹⁾	(2)	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000	
98h	TXSTA	CSRC	TX9	TXEN	SYNC	_	BRGH	TRMT	TX9D	0000 -010	0000 -010	
99h	SPBRG	Baud Rate	Baud Rate Generator Register								0000 0000	

2: PIE1<6> and PIR1<6> are reserved, always maintain these bits clear.

FIGURE 12-12: SYNCHRONOUS TRANSMISSION

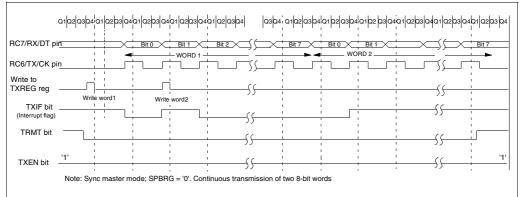
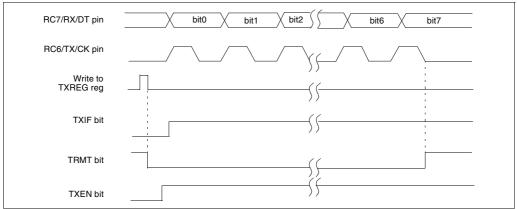


FIGURE 12-13: SYNCHRONOUS TRANSMISSION THROUGH TXEN



13.4 Power-on Reset (POR), Power-up Timer (PWRT), Oscillator Start-up Timer (OST) and Brown-out Reset (BOR)

Applicable Devices 61|62|62A|R62|63|R63|64|64A|R64|65|65A|R65|66|67

13.4.1 POWER-ON RESET (POR)

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the POR, just tie the \overline{MCLR}/VPP pin directly (or through a resistor) to VDD. This will eliminate external RC components usually needed to create a Power-on Reset. A maximum rise time for VDD is required. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met. Brown-out Reset may be used to meet the startup conditions.

For additional information, refer to Application Note AN607, "*Power-up Trouble Shooting*."

13.4.2 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 72 ms nominal time-out on power-up only, from POR. The Power-up Timer operates on an internal RC oscillator. The chip is kept in reset as long as PWRT is active. The PWRT's time delay allows VDD to rise to an acceptable level. A configuration bit is provided to enable/disable the PWRT.

The power-up time delay will vary from chip to chip due to VDD, temperature, and process variation. See DC parameters for details.

13.4.3 OSCILLATOR START-UP TIMER (OST)

The Oscillator Start-up Timer (OST) provides 1024 oscillator cycle (from OSC1 input) delay after the PWRT delay is over. This ensures the crystal oscillator or resonator has started and stabilized.

The OST time-out is invoked only for XT, LP and HS modes and only on Power-on Reset or wake-up from SLEEP.

13.4.4 BROWN-OUT RESET (BOR)

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

A configuration bit, BODEN, can disable (if clear/programmed) or enable (if set) the Brown-out Reset circuitry. If VDD falls below 4.0V (parameter D005 in Electrical Specification section) for greater than parameter #34 (see Electrical Specification section), the brown-out situation will reset the chip. A reset may not occur if VDD falls below 4.0V for less than parameter #34. The chip will remain in Brown-out Reset until VDD rises above BVDD. The Power-up Timer will now be invoked and will keep the chip in RESET an additional 72 ms. If VDD drops below BVDD while the Power-up Timer is running, the chip will go back into a Brown-out Reset and the Power-up Timer will be initialized. Once VDD rises above BVDD, the Power-up Timer will execute a 72 ms time delay. The Power-up Timer should always be enabled when Brown-out Reset is enabled. Figure 13-10 shows typical brown-out situations.

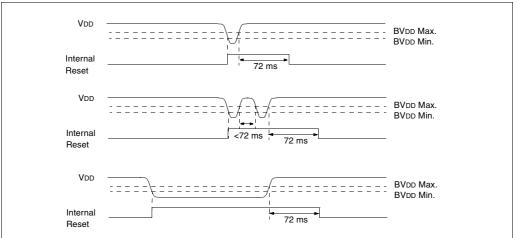


FIGURE 13-10: BROWN-OUT SITUATIONS

13.5 Interrupts

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The PIC16C6X family has up to 11 sources of interrupt. The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note:	Individual interrupt flag bits are set regard-
	less of the status of their corresponding
	mask bit or global enable bit, GIE.

Global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in the INTCON register. GIE is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enable interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flag bits are contained in the INTCON register.

The peripheral interrupt flag bits are contained in special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2 and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, bit GIE is cleared to disable any further interrupts, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the RB0/INT pin or RB port change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 13-19). The latency is the same for one or two cycle instructions. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid infinite interrupt requests. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

- Note: For the PIC16C61/62/64/65, if an interrupt occurs while the Global Interrupt Enable bit, GIE is being cleared, bit GIE may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:
 - 1. An instruction clears the GIE bit while an interrupt is acknowledged
 - 2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
 - The Interrupt Service Routine completes with the execution of the RET-FIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.
 - 4. Perform the following to ensure that interrupts are globally disabled.

LOOP	BCF II	NTCON,GIE	;Disable Global
			;Interrupt bit
	BTFSC	INTCON,GIE	;Global Interrupt
			;Disabled?
	GOTO	LOOP	;NO, try again
	:		;Yes, continue
			;with program flow

BTFSS	Bit Test f	, Skip if S	Set		_	CALL	Call Sub	routine		
Syntax:	[<i>label</i>] BT	FSS f,b				Syntax:	[label]	CALL k		
Operands:	$0 \leq f \leq 12$	7				Operands:	$0 \le k \le 2$	047		
	0 ≤ b < 7					Operation:	(PC)+ 1-	,		
Operation:	skip if (f <l< td=""><td>b>) = 1</td><td></td><td></td><td></td><td></td><td>$k \rightarrow PC <$</td><td>,</td><td></td><td>44.</td></l<>	b>) = 1					$k \rightarrow PC <$,		44.
Status Affected:	None		1		7	o	(PCLATH	1<4:3>) -	> PG<12:	11>
Encoding:	01	11bb	bfff	ffff		Status Affected:	None	1		·
Description:	If bit 'b' in r instruction			ne next		Encoding:	10	0kkk	kkkk	kkkk
	If bit 'b' is ' discarded instead, m	1', then the and a NOF	e next instr s execute	əd		Description:	(PC+1) is eleven bit into PC bit	putine. Firs pushed on immediate ts <10:0>.	to the stac address is The upper	k. The s loaded bits of
Words:	1						the PC are is a two cy			H. CALL
Cycles:	1(2)					Words:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4	-	Cycles:	2			
	Decode	Read register 'f'	Process data	No- Operation		Q Cycle Activity:	Q1	Q2	Q3	Q4
If Skip:	(2nd Cyc	le)				1st Cycle	Decode	Read literal 'k',	Process data	Write to PC
·	Q1	Q2	Q3	Q4	7			Push PC to Stack	uulu	10
	No- Operation	No- Operation	No- Operation	No- Operation		2nd Cycle	No- Operation	No- Operation	No- Operation	No- Operation
Example	HERE FALSE	BTFSC GOTO	FLAG,1 PROCESS	CODE		Example	HERE	CALL	THERE	
	TRUE	•						PC = A	ddress HE	RE
		•					After Inst	truction PC = A	ddroce TTU	סמס
	Before In:		address I	TEDE				TOS = A		
	After Inst		address r	IERE						
		f FLAG<1:	- /							
		PC = if FLAG<1;	address Fi	ALSE						
			> = 1, address TI	RUE						

XORLW	Exclusiv	/e OR Li	teral wit	h W
Syntax:	[<i>label</i>]	XORLV	Vk	
Operands:	$0 \le k \le 2$	55		
Operation:	(W) .XO	$R. k \to (N$	N)	
Status Affected:	Z			
Encoding:	11	1010	kkkk	kkkk
Description:	The conte XOR'ed v The resul ter.	vith the eig	ght bit lite	ral 'k'.
Words:	1			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read literal 'k'	Process data	Write to W
Example:	XORLW	0xAF		
	Before Ir	nstruction	n	
		W =	0xB5	
	After Ins	truction		
		W =	0x1A	

XORWF	Exclusiv	e OR W	with f	
Syntax:	[label]	XORWF	f,d	
Operands:	$\begin{array}{l} 0 \leq f \leq 12 \\ d \in [0,1] \end{array}$	27		
Operation:	(W) .XOF	$R.(f) \to (f)$	destinatio	on)
Status Affected:	Z			
Encoding:	00	0110	dfff	ffff
Description:	Exclusive register wi result is st 1 the resu	th registe ored in the	r 'f'. If 'd' is e W regist	s 0 the er. If 'd' is
Words:	1			
Cycles:	1			
Q Cycle Activity:	Q1	Q2	Q3	Q4
	Decode	Read register 'f'	Process data	Write to destination
Example	XORWF	REG	1	
	Before In	struction	I	
		REG W	0/1	AF B5
	After Inst	ruction		
		REG W	0/1	1A B5

=

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 15-5: TIMER0 EXTERNAL CLOCK TIMINGS

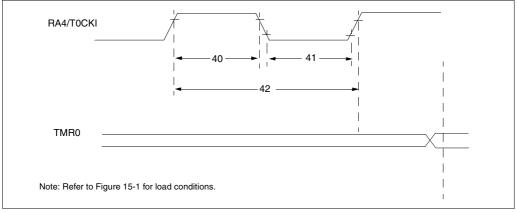
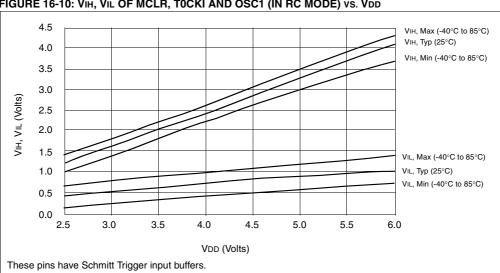


TABLE 15-5: TIMER0 EXTERNAL CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5Tcy + 20	_	_		Must also meet
			With Prescaler	10	—	_	ns	parameter 42
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5TCY + 20	—	—		Must also meet
			With Prescaler	10	—	—	ns	parameter 42
42*	Tt0P	T0CKI Period	No Prescaler	TCY + 40	_	_		N = prescale value
			With Prescaler	Greater of: 20 ns or <u>Tcy + 40</u> N	_	_	ns	(2, 4,, 256)

These parameters are characterized but not tested.

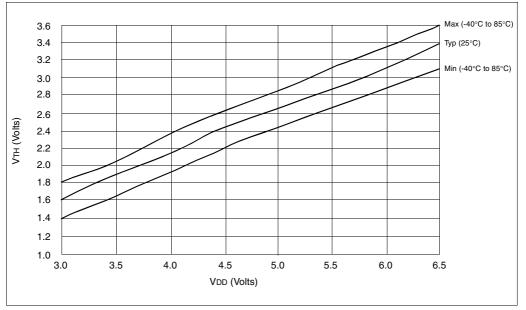
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.



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FIGURE 16-10: VIH, VIL OF MCLR, TOCKI AND OSC1 (IN RC MODE) vs. VDD





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18.4 <u>Timing Parameter Symbology</u>

The timing parameter symbols have been created following one of the following formats:

1. TppS2	opS	3. Tcc:st	(I ² C specifications only)
2. TppS		4. Ts	(I ² C specifications only)
т			
F	Frequency	т	Time
Lowerc	ase letters (pp) and their meanings:		
рр			
сс	CCP1	osc	OSC1
ck	CLKOUT	rd	RD
cs	CS	rw	RD or WR
di	SDI	SC	SCK
do	SDO	SS	SS
dt	Data in	tO	TOCKI
io	I/O port	t1	T1CKI
mc	MCLR	wr	WR
1	ase letters and their meanings:		
S			
F	Fall	P	Period
Н	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance
I ² C only			
AA	output access	High	High
BUF	Bus free	Low	Low
Tcc:st	(I ² C specifications only)		
CC			
HD	Hold	SU	Setup
ST			
DAT	DATA input hold	STO	STOP condition
STA	START condition		
FIGURE	18-1: LOAD CONDITIONS FOR DEVI	CE TIMING S	SPECIFICATIONS
	Load condition 1		Load condition 2
	N/ /0		
	VDD/2		
	J		
	\leq RL		
	\leq		· ····
	• • • • • • • • • • • • • • • • • • •		Vss
	+		
	Vss	RL = 464Ω	
			for all pipe execut OSC2/CL/CUT
		CL = 50 pF	for all pins except OSC2/CLKOUT but including D and E outputs as ports
Note 1:	PORTD and PORTE are not	15-5	÷
	implemented on the	15 pF	for OSC2 output
	PIC16C62A/R62.		

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NOTES:

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20.2 DC Characteristics: PIC16LC63/65A-04 (Commercial, Industrial)

DC CHA		Standaı Operatir		•		°C ≤	Inless otherwise stated) TA \leq +85°C for industrial and TA \leq +70°C for commercial
Param No.	Characteristic	Sym	Min	Тур†	Max	Units	Conditions
D001	Supply Voltage	Vdd	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	Vdr	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	Vss	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2, 5)	IDD	-	2.0	3.8	mA	XT, RC osc configuration Fosc = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration Fosc = 32 kHz, VDD = 3.0V, WDT disabled
D015*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V
D020	Power-down Current	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021	(Note 3, 5)		-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D023*	Brown-out Reset Current (Note 6)	Δ IBOR	-	350	425	μA	BOR enabled, VDD = 5.0V

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD,

- $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.
- 3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.
- 4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.
- 5: Timer1 oscillator (when enabled) adds approximately 20 μA to the specification. This value is from characterization and is for design guidance only. This is not tested.
- 6: The ∆ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

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20.5 <u>Timing Diagrams and Specifications</u>

FIGURE 20-2: EXTERNAL CLOCK TIMING

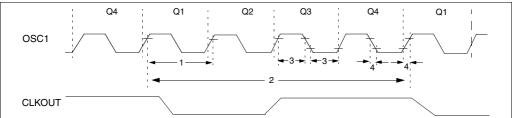


TABLE 20-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
	Fosc	External CLKIN Frequency	DC	I	4	MHz	XT and RC osc mode
		(Note 1)	DC	_	4	MHz	HS osc mode (-04)
			DC	_	10	MHz	HS osc mode (-10)
			DC	_	20	MHz	HS osc mode (-20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency	DC	-	4	MHz	RC osc mode
		(Note 1)	0.1	_	4	MHz	XT osc mode
			4	_	20	MHz	HS osc mode
			5	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250		—	ns	XT and RC osc mode
		(Note 1)	250	_	_	ns	HS osc mode (-04)
			100	_	_	ns	HS osc mode (-10)
			50	_	_	ns	HS osc mode (-20)
			5	_	_	μs	LP osc mode
		Oscillator Period	250		_	ns	RC osc mode
		(Note 1)	250	_	10,000	ns	XT osc mode
			250	_	250	ns	HS osc mode (-04)
			100	_	250	ns	HS osc mode (-10)
			50	_	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	Тсү	Instruction Cycle Time (Note 1)	200	Тсү	DC	ns	Tcy = 4/Fosc
3*	TosL,	External Clock in (OSC1) High or	100	_	_	ns	XT oscillator
	TosH	Low Time	2.5	—	—	μs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR,	External Clock in (OSC1) Rise or	—	_	25	ns	XT oscillator
	TosF	Fall Time	—	—	50	ns	LP oscillator
			_	_	15	ns	HS oscillator

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TcY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

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FIGURE 20-3: CLKOUT AND I/O TIMING

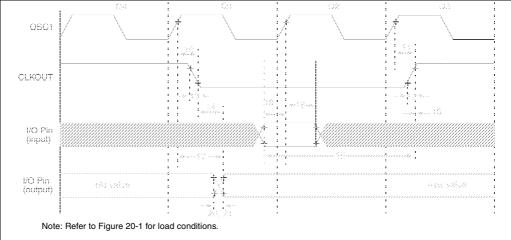


TABLE 20-3:	CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		_	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		_	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		_	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		_	_	0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	Port in valid before CLKOUT 1		_	-	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑		0	_	_	ns	Note 1
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out val	lid	_	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input	PIC16 C 63/65A	100	_	_	ns	
		invalid (I/O in hold time)	PIC16LC63/65A	200	_	_	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O in	setup time)	0	_	_	ns	
20*	TioR	Port output rise time	PIC16 C 63/65A	_	10	40	ns	
			PIC16LC63/65A	_	_	80	ns	
21*	TioF	Port output fall time	PIC16 C 63/65A	_	10	40	ns	
			PIC16LC63/65A	_	_	80	ns	
22††*	Tinp	INT pin high or low time	1	TCY	_	_	ns	
23††*	Trbp	RB7:RB4 change INT high or low	/ time	Тсү	—	_	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

tt These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

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FIGURE 22-14: I²C BUS DATA TIMING

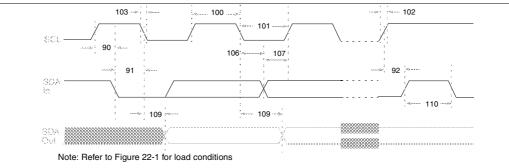


TABLE 22-10: I²C BUS DATA REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100*	Тнідн	Clock high time	100 kHz mode	4.0	-	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	0.6	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5TCY	—		
101*	TLOW	Clock low time	100 kHz mode	4.7	_	μs	Device must operate at a mini- mum of 1.5 MHz
			400 kHz mode	1.3	_	μs	Device must operate at a mini- mum of 10 MHz
			SSP Module	1.5Tcy	—		
102*	TR	SDA and SCL rise	100 kHz mode	-	1000	ns	
		time	400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103*	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90*	TSU:STA	START condition	100 kHz mode	4.7	—	μs	Only relevant for repeated
		setup time	400 kHz mode	0.6	—	μs	START condition
91*	THD:STA	START condition hold	100 kHz mode	4.0	—	μs	After this period the first clock
		time	400 kHz mode	0.6	—	μs	pulse is generated
106*	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	-
107*	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92*	Tsu:sto	STOP condition setup	100 kHz mode	4.7	—	μs	
		time	400 kHz mode	0.6	—	μs	
109*	TAA	Output valid from	100 kHz mode	_	3500	ns	Note 1
		clock	400 kHz mode	—	—	ns	
110*	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free
			400 kHz mode	1.3	—	μs	before a new transmission can start
	Cb	Bus capacitive loading		—	400	pF	

These parameters are characterized but not tested.

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

2: A fast-mode (400 kHz) I²C-bus device can be used in a standard-mode (100 kHz) I²C-bus system, but the requirement Tsu:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line TR max.+tsu;DAT = 1000 + 250 = 1250 ns (according to the standard-mode I²C bus specification) before the SCL line is released. Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 22-15: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

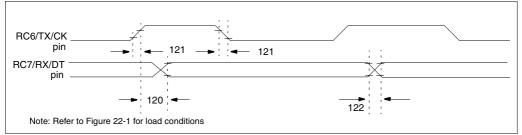


TABLE 22-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Тур†	Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE)	PIC16 C 66/67		—	80	ns	
		Clock high to data out valid	PIC16 LC 66/67	-	—	100	ns	
121*	Tckrf	Clock out rise time and fall time	PIC16 C 66/67		—	45	ns	
		(Master Mode)	PIC16LC66/67		—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16 C 66/67	_	—	45	ns	
			PIC16LC66/67	_	—	50	ns	

* These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 22-16: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

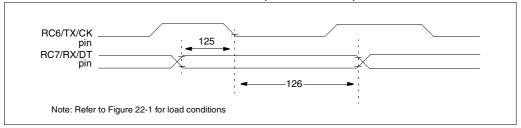


TABLE 22-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
125*	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data setup before CK \downarrow (DT setup time)	15		_	ns	
126*	TckL2dtl	Data hold after CK \downarrow (DT hold time)	15	_	_	ns	

These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TMR0
TMR0 Clock Source Select bit, T0CS
TMR0 Interrupt
TMR0 Overflow Interrupt Enable bit, T0IE
TMR0 Overflow Interrupt Flag bit, T0IF
TMR0 Prescale Selection Table
TMR0 Source Edge Select bit, T0SE
TMR1 Overflow Interrupt Enable bit, TMR1IE
TMR1 Overflow Interrupt Flag bit, TMR1IF
TMR1CS
TMR1H
TMR1IE
TMR1IF
TMR1L
TMR10N
TMR2
TMR2 Register
TMR2 to PR2 Match Interrupt Enable bit, TMR2IE
TMR2 to PR2 Match Interrupt Flag bit, TMR2IF
TMR216 TH2 Match menupit hag bit, TMR217
TMR2IE
TMR20N
TO
TOUTPS3:TOUTPS0
Transmit Enable bit, TXEN
Transmit Enable bit, TXEN
Transmit Status and Control Register
TRISA
TRISB
TRISC
TRISD
TRISE
TRMT
TX9
TX9D105
TXEN
TXIE
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TXSTA
U

L

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хт	
7	
2	
Ζ	
Zero bit	